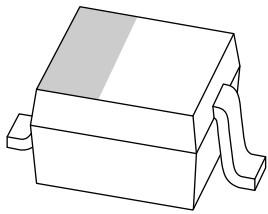


# DATA SHEET



## **BB156**

Low-voltage variable capacitance diode

Product specification  
Supersedes data of 1998 Aug 17

2004 Mar 01



# Low-voltage variable capacitance diode

**BB156**

### FEATURES

- Excellent linearity
- Very small plastic SMD package
- C7.5: 4.8 pF; ratio 3.3
- Very low series resistance.

### APPLICATIONS

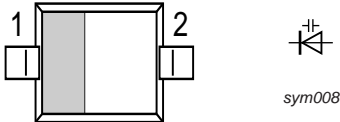
- Voltage controlled oscillators (VCO).

### DESCRIPTION

The BB156 is a planar technology variable capacitance diode, in a SOD323 very small plastic SMD package.

### PINNING

PIN	DESCRIPTION
1	cathode
2	anode



Marking code: PF.  
The marking bar indicates the cathode.

Fig.1 Simplified outline (SOD323; SC-76) and symbol.

### ORDERING INFORMATION

TYPE NUMBER	PACKAGE		
	NAME	DESCRIPTION	VERSION
BB156	–	plastic surface mounted package; 2 leads	SOD323

### LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 60134).

SYMBOL	PARAMETER	MIN.	MAX.	UNIT
$V_R$	continuous reverse voltage	–	10	V
$I_F$	continuous forward current	–	20	mA
$T_{stg}$	storage temperature	–55	+150	°C
$T_j$	operating junction temperature	–55	+125	°C

## Low-voltage variable capacitance diode

BB156

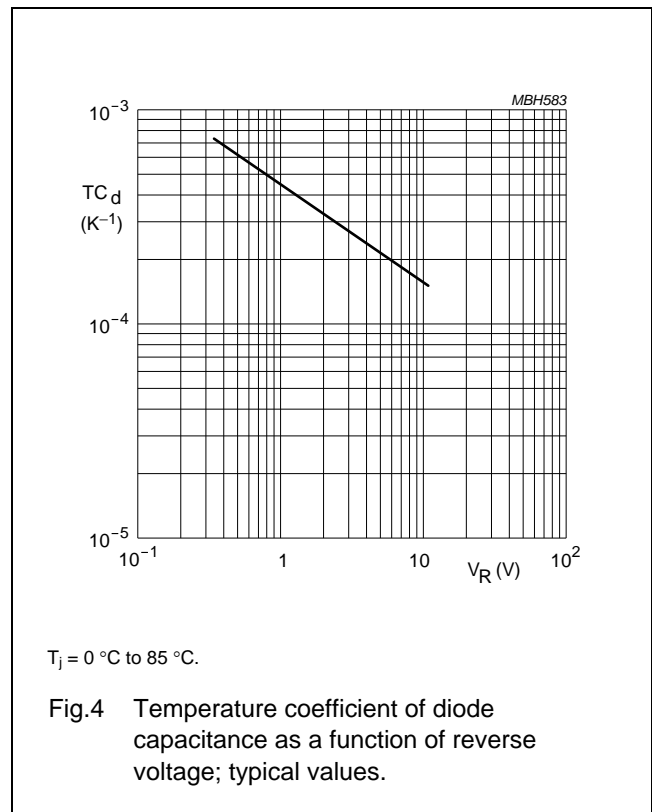
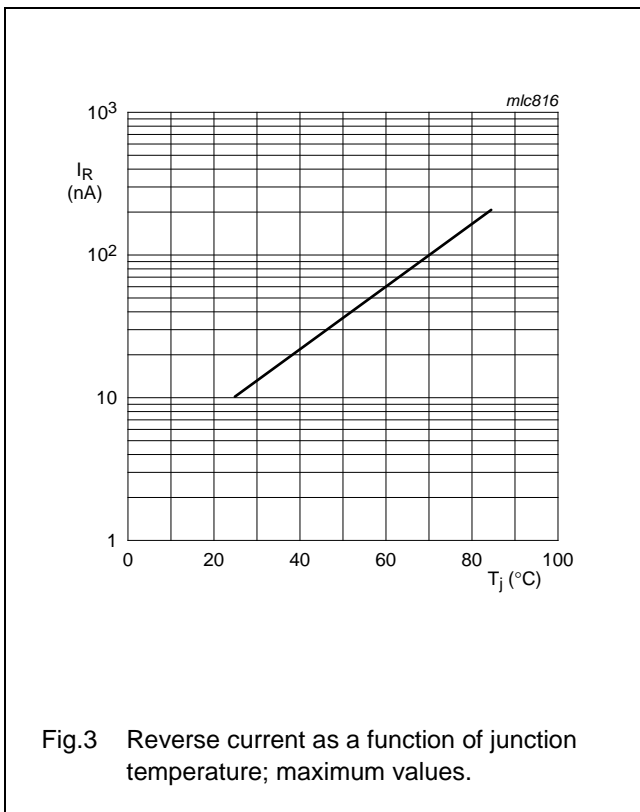
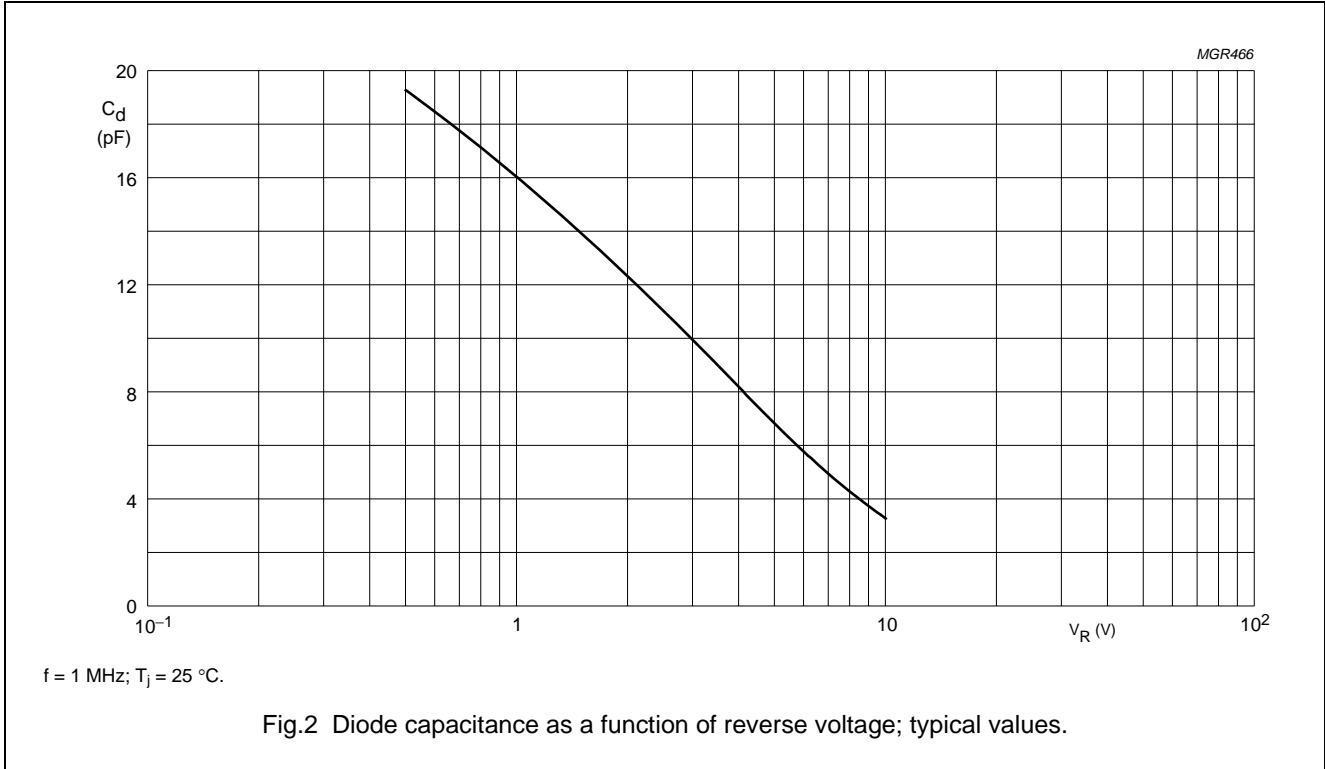
**ELECTRICAL CHARACTERISTICS** $T_j = 25\text{ °C}$  unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
$I_R$	reverse current	$V_R = 10\text{ V}$ ; see Fig.3	–	–	10	nA
		$V_R = 10\text{ V}$ ; $T_j = 85\text{ °C}$ ; see Fig.3	–	–	200	nA
$r_s$	diode series resistance	$f = 470\text{ MHz}$ ; $C_d = 9\text{ pF}$	–	0.4	0.7	$\Omega$
$C_d$	diode capacitance	$f = 1\text{ MHz}$ ; see Figs 2 and 4				
		$V_R = 1\text{ V}$	14.4	16	17.6	pF
		$V_R = 4\text{ V}$	7.6	8.6	9.6	pF
		$V_R = 7.5\text{ V}$	4.2	4.8	5.4	pF
$\frac{C_{d(1\text{ V})}}{C_{d(7.5\text{ V})}}$	capacitance ratio	$f = 1\text{ MHz}$	2.7	3.3	3.9	

Low-voltage variable capacitance diode

BB156

GRAPHICAL DATA



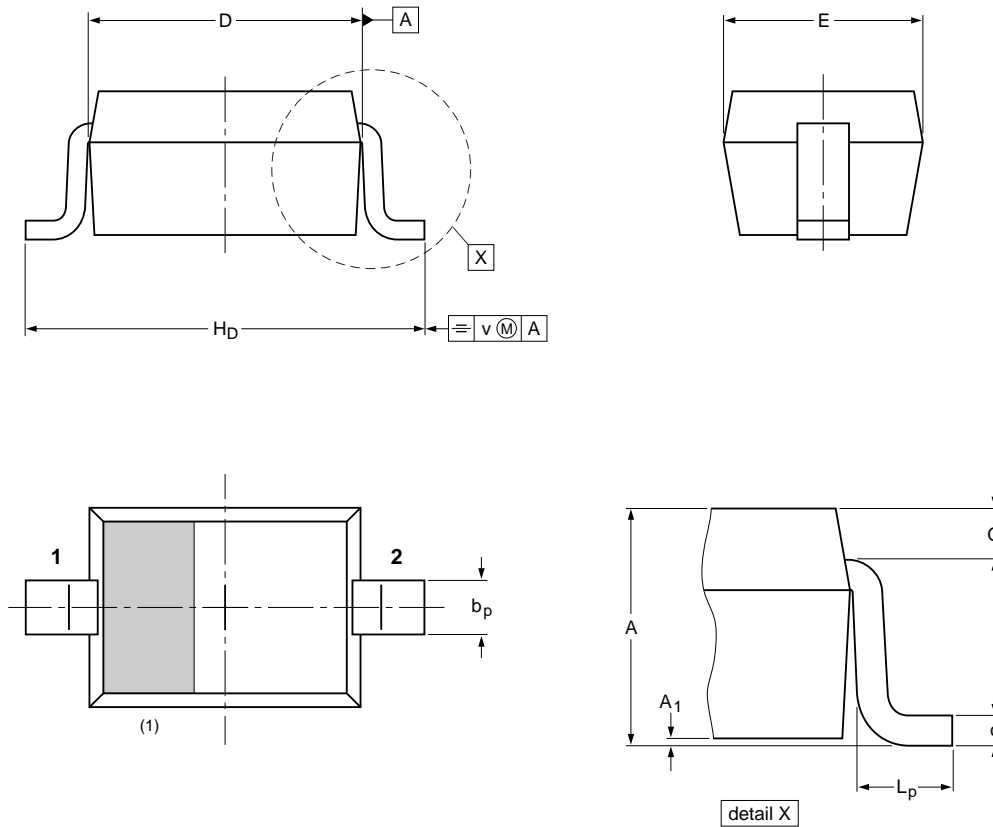
Low-voltage variable capacitance diode

BB156

PACKAGE OUTLINE

Plastic surface-mounted package; 2 leads

SOD323



DIMENSIONS (mm are the original dimensions)

UNIT	A	A <sub>1</sub> max	b <sub>p</sub>	c	D	E	H <sub>D</sub>	L <sub>p</sub>	Q	v
mm	1.1 0.8	0.05	0.40 0.25	0.25 0.10	1.8 1.6	1.35 1.15	2.7 2.3	0.45 0.15	0.25 0.15	0.2

Note

1. The marking bar indicates the cathode

OUTLINE VERSION	REFERENCES			EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA		
SOD323			SC-76		-03-12-17- 06-03-16

## Low-voltage variable capacitance diode

BB156

## DATA SHEET STATUS

DOCUMENT STATUS <sup>(1)</sup>	PRODUCT STATUS <sup>(2)</sup>	DEFINITION
Objective data sheet	Development	This document contains data from the objective specification for product development.
Preliminary data sheet	Qualification	This document contains data from the preliminary specification.
Product data sheet	Production	This document contains the product specification.

## Notes

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## Low-voltage variable capacitance diode

BB156

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## **Customer notification**

This data sheet was changed to reflect the new company name NXP Semiconductors, including new legal definitions and disclaimers. No changes were made to the technical content, except for package outline drawings which were updated to the latest version.

## **Contact information**

For additional information please visit: <http://www.nxp.com>

For sales offices addresses send e-mail to: [salesaddresses@nxp.com](mailto:salesaddresses@nxp.com)

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Printed in The Netherlands

R77/02/pp8

Date of release: 2004 Mar 01